

SRM20256LT_{10/12}

CMOS 256K-BIT STATIC RAM

• Industrial Temperature Range

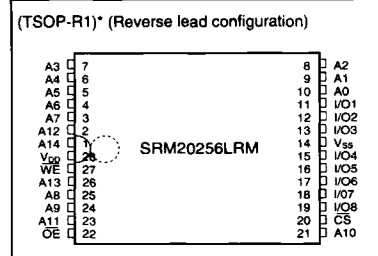
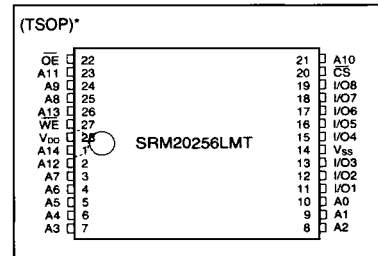
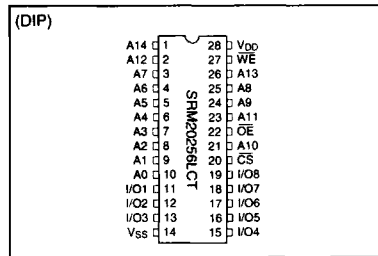
DESCRIPTION

The SRM20256LT_{10/12} is a 32,768 word x 8 bits asynchronous, static, random access memory fabricated using an advanced CMOS technology. Its very low standby power feature makes it ideal for applications requiring non-volatile storage with back-up batteries. And -40 to 85°C operating temperature range makes it ideal for industrial use. The asynchronous and static nature of the memory requires no external clock or refresh circuit. Input and output ports are TTL compatible and the three-state output allows easy expansion of memory capacity.

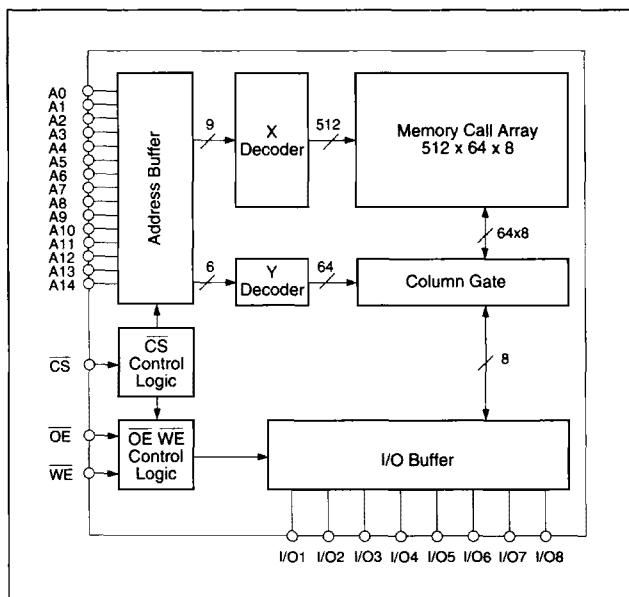
FEATURES

- Industrial temperature range -40 to 85°C
- Fast access time SRM20256LT₁₀ 100ns (Max)
..... SRM20256LT₁₂ 120ns (Max)
- Low supply current Standby : 2µA (Typ)
..... Operation: 13mA/1MHz (Typ)
- Completely static No clock required
- Single power supply 5V ± 10%
- TTL compatible inputs and outputs
- 3-state output
- Battery back-up operation
- Package SRM20256LCT_{10/12} 28-pin DIP (plastic)
SRM20256LMT_{10/12} 28-pin TSOP (plastic)
SRM20256LTMT_{10/12} 28-pin TSOP (plastic)
SRM20256LRMT_{10/12} 28-pin RTSOP (plastic)

PIN CONFIGURATION



BLOCK DIAGRAM



PIN DESCRIPTION

| | |
|-----------|--------------------|
| A0 to A14 | Address Input |
| WE | Write enable |
| OE | Output Enable |
| CS | Chip Select |
| I/O1 to 8 | Data I/O |
| VDD | Power Supply (+5V) |
| VSS | Power Supply (0V) |

■ ABSOLUTE MAXIMUM RATINGS

(V_{SS}=0V)

| Parameter | Symbol | Ratings | Unit |
|--------------------------------|------------------|-------------------------------|------|
| Supply voltage | V _{DD} | -0.5 to 7.0 | V |
| Input voltage * | V _I | -0.5 to 7.0 | V |
| Input/Output voltage* | V _{I/O} | -0.5* to V _{DD} +0.3 | V |
| Power dissipation | P _D | 1.0 | W |
| Operating temperature | T _{opr} | -40 to 85 | °C |
| Storage temperature | T _{stg} | -65 to 150 | °C |
| Soldering temperature and time | T _{sol} | 260°C, 10s (at lead) | — |

* V_I, V_{I/O} (Min) = -1.0V when pulse width is less than or equal to 50 ns

■ RECOMMENDED DC OPERATING CONDITIONS

(V_{SS}=0V, T_a = -40 to 85°C)

| Parameter | Symbol | Min | Typ | Max | Unit |
|----------------|-----------------|--------|-----|-----------------------|------|
| Supply Voltage | V _{DD} | 4.5 | 5.0 | 5.5 | V |
| | V _{SS} | 0 | 0 | 0 | V |
| Input Voltage | V _{IH} | 2.2 | 3.5 | V _{DD} + 0.3 | V |
| | V _{IL} | -0.3 * | — | 0.8 | V |

* V_{IL} (Min) = -1.0V when pulse width is less than or equal to 50ns

■ ELECTRICAL CHARACTERISTICS

● DC Electrical Characteristics

(V_{DD} = 5V ± 10%, V_{SS} = 0V, T_a = -40 to 85°C)

| Parameter | Symbol | Conditions | SRM20256LT10 | | | SRM20256LT12 | | | Unit |
|---------------------------|-------------------|---|--------------|----------------------|-----|--------------|----------------------|-----|------|
| | | | Min | Typ* | Max | Min | Typ* | Max | |
| Input leakage current | I _{LI} | V _I = 0 to V _{DD} | -1 | — | 1 | -1 | — | 1 | μA |
| Standby supply current | I _{DDS} | $\overline{CS} = V_{IH}$ | — | 1.5 | 3.0 | — | 1.5 | 3.0 | mA |
| | I _{DDS1} | $CS \geq V_{DD} - 0.2V$ | — | 2 | 200 | — | 2 | 200 | μA |
| Average operating current | I _{DDA} | V _I =V _{IL} , V _{IH} , I _{I/O} = 0mA, t _{cyc} =Min | — | 40 | 70 | — | 37 | 70 | mA |
| | I _{DDA1} | V _I =V _{IL} , V _{IH} , I _{I/O} = 0mA, t _{cyc} =1μs | — | 13 | — | — | 13 | — | mA |
| Operating supply current | I _{DDO} | V _I =V _{IL} , V _{IH} , I _{I/O} = 0mA | — | 35 | 65 | — | 35 | 65 | mA |
| Output leakage current | I _{LO} | $\overline{CS} = V_{IH}$, or $\overline{WE} = V_{IL}$, or $\overline{OE} = V_{IH}$, V _{I/O} = 0 to V _{DD} | -1 | — | 1 | -1 | — | 1 | μA |
| High level output voltage | V _{OH} | I _{OH} =-1.0mA | 2.4 | V _{DD} -0.1 | — | 2.4 | V _{DD} -0.1 | — | V |
| Low level output voltage | V _{OL} | I _{OL} =2.1mA | — | 0.2 | 0.4 | — | 0.2 | 0.4 | V |

● Terminal Capacitance

(f = 1MHz, T_a = 25°C)

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|---------------------|------------------|-----------------------|-----|-----|-----|------|
| Address capacitance | C _{ADD} | V _{ADD} = 0V | — | — | 10 | pF |
| Input capacitance | C _I | V _I = 0V | — | — | 10 | pF |
| I/O capacitance | C _{I/O} | V _{I/O} = 0V | — | — | 10 | pF |

● AC Electrical Characteristics

O Read Cycle

(V_{DD} = 5V ± 10%, V_{SS} = 0V, T_a = -40 to 85°C)

| Parameter | Symbol | Conditions | SRM2264L10 | | SRM2264L12 | | Unit |
|-------------------------|------------------|------------|------------|-----|------------|-----|------|
| | | | Min | Max | Min | Max | |
| Read cycle time | t _{RC} | *1 | 100 | — | 120 | — | ns |
| Address access time | t _{ACC} | | — | 100 | — | 120 | ns |
| CS access time | t _{ACS} | | — | 100 | — | 120 | ns |
| OE access time | t _{OE} | | — | 50 | — | 60 | ns |
| CS output set time | t _{CLZ} | *2 | 10 | — | 10 | — | ns |
| CS output floating time | t _{CHZ} | | — | 35 | — | 40 | ns |
| OE output set time | t _{OLZ} | | 5 | — | 5 | — | ns |
| OE output floating time | t _{OHZ} | | — | 35 | — | 40 | ns |
| Output hold time | t _{OH} | | *1 | 10 | — | 10 | — |

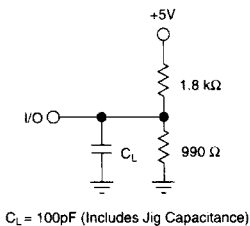
O Write Cycle

(V_{DD} = 5V ± 10%, V_{SS} = 0V, T_a = -40 to 85°C)

| Parameter | Symbol | Conditions | SRM20256LC10 | | SRM20256LC12 | | Unit |
|---------------------------------|------------------|------------|--------------|-----|--------------|-----|------|
| | | | Min | Max | Min | Max | |
| Write cycle time | t _{WC} | *1 | 100 | — | 120 | — | ns |
| Chip select time | t _{CW} | | 80 | — | 85 | — | ns |
| Address valid to end of write | t _{AW} | | 80 | — | 85 | — | ns |
| Address setup time | t _{AS} | | 0 | — | 0 | — | ns |
| Write pulse width | t _{WP} | | 75 | — | 80 | — | ns |
| Address hold time | t _{WR} | | 5 | — | 5 | — | ns |
| Input data set time | t _{DW} | | 45 | — | 50 | — | ns |
| Input data hold time | t _{DH} | | 0 | — | 0 | — | ns |
| Write to output floating | t _{WHZ} | *2 | — | 35 | — | 40 | ns |
| Output active from end of write | t _{OW} | | 5 | — | 5 | — | ns |

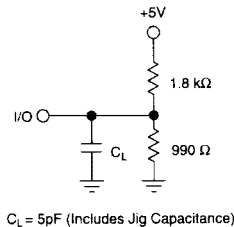
***1 Test conditions**

1. Input pulse level: 0.6V to 2.4V
2. t_r = t_f = 5ns
3. Input and output timing reference levels: 1.5V
4. Output load C_L = 100pF

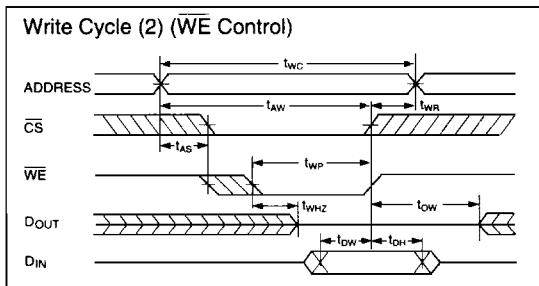
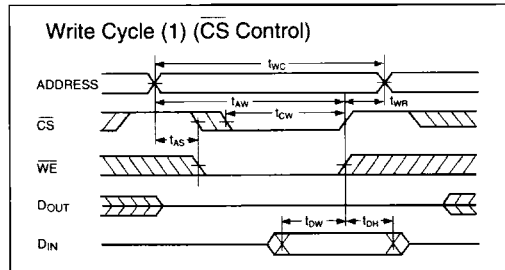
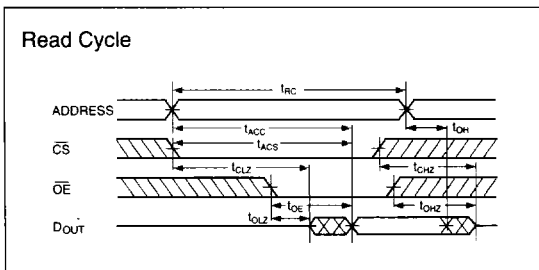


***2 Test conditions**

1. Input pulse level : 0.6V to 2.4V
2. t_r = t_f = 5ns
3. Input timing reference levels: 1.5V
4. Output timing reference levels: ±200mV (the level displaced from stable output voltage level)
5. Output load C_L = 5pF



● Timing Chart



Note:

1. During read cycle time, \overline{WE} is to be "H" level.
2. Write cycle time is controlled by CS. Output Buffer is in high impedance state, whether OE is "H" or "L".
3. Write cycle time that is controlled by WE, Output Buffer is in high impedance state.

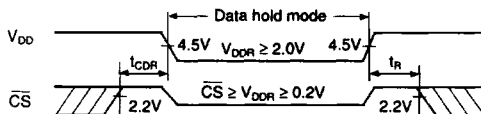
■ DATA RETENTION CHARACTERISTICS WITH LOW VOLTAGE POWER SUPPLY

(V_{SS} = 0V, T_a = -40 to 85°C)

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|-------------------------------|------------------|--|-------------------|-----|-----|------|
| Data retention supply voltage | V _{DDR} | | 2.0 | — | 5.5 | V |
| Data retention supply current | I _{DDR} | V _{DD} = 3V, CS ≥ V _{DDR} - 0.2V | — | 1 | 100 | μA |
| Chip select data hold time | t _{CDR} | | 0 | — | — | ns |
| Operation recovery time | t _R | | t _{RC} * | — | — | ns |

* t_{RC} = Read cycle time

Data retention timing



■ FUNCTIONS

● Truth Table

| $\overline{\text{CS}}$ | $\overline{\text{OE}}$ | $\overline{\text{WE}}$ | A0 to A14 | DATA I/O | MODE | I _{DD} |
|------------------------|------------------------|------------------------|-----------|------------------|----------------|---------------------------------------|
| H | — | — | — | Hi-Z | Standby | I _{DD} S, I _{DD} S1 |
| L | X | L | Stable | D _{IN} | Write | I _{DD} A, I _{DD} A1 |
| L | L | H | Stable | D _{OUT} | Read | I _{DD} A, I _{DD} A1 |
| L | H | H | Stable | Hi-Z | Output disable | I _{DD} A, I _{DD} A1 |

X: "H" or "L"

● Reading Data

Data can be read out if an address is set while $\overline{\text{CS}} = \text{"L"}$, $\overline{\text{OE}} = \text{"L"}$, and $\overline{\text{WE}} = \text{"H"}$. When $\overline{\text{OE}} = \text{"H"}$, Data I/O terminals are in high impedance state; that makes it easy for circuit design and bus control.

● Writing Data

There are the following three ways of writing data into the memory.

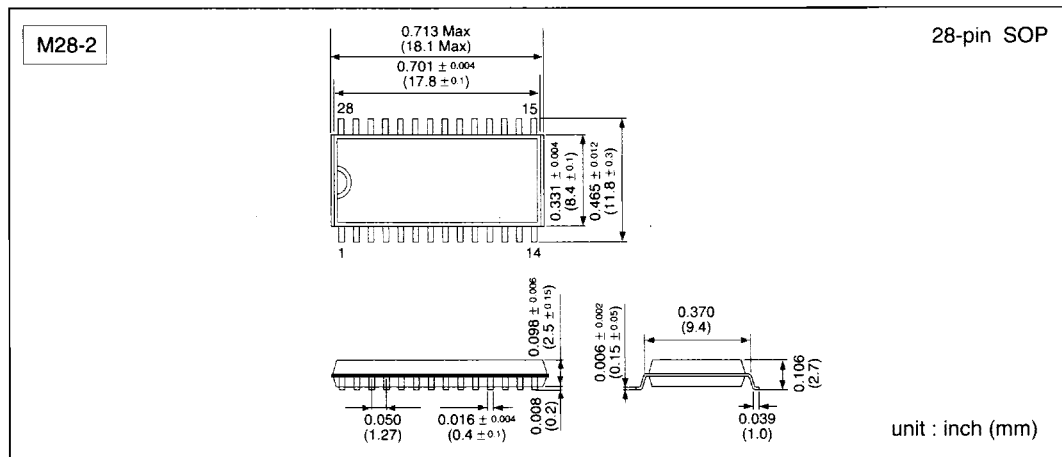
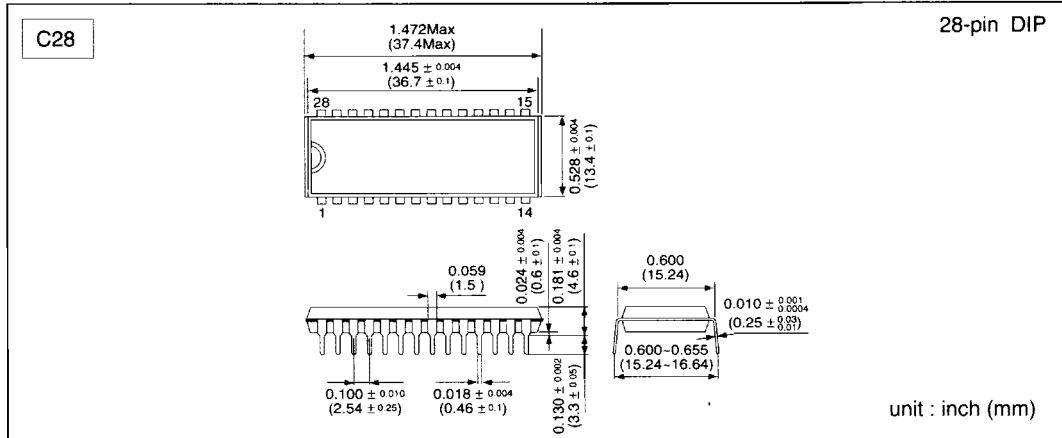
- (1) Hold $\overline{\text{CS}}$ low, set the address, and apply a low pulse to $\overline{\text{WE}}$.
- (2) Hold $\overline{\text{R/W}}$ low, set the address, and apply a low pulse to $\overline{\text{WE}}$.
- (3) Set the address, then apply low pulses to both $\overline{\text{CS}}$ and $\overline{\text{WE}}$.

In each case, data from the DATA I/O terminal is latched into the SRM20256LT10/12 when $\overline{\text{CS}}$ or $\overline{\text{WE}}$ is positive. Since DATA I/O terminals are in high impedance state when $\overline{\text{CS}}$ or $\overline{\text{OE}} = \text{"H"}$, the contention on the data bus can be avoided.

● Standby Mode

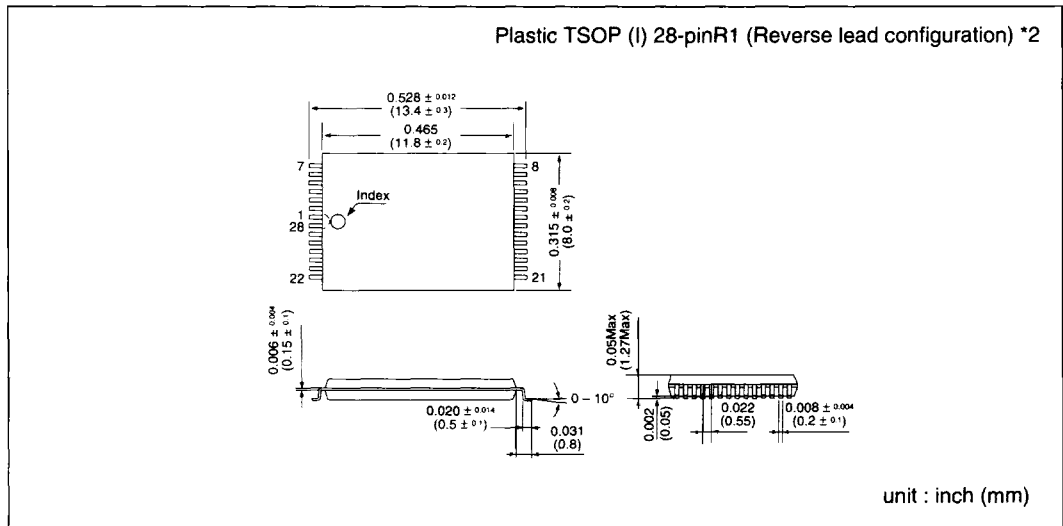
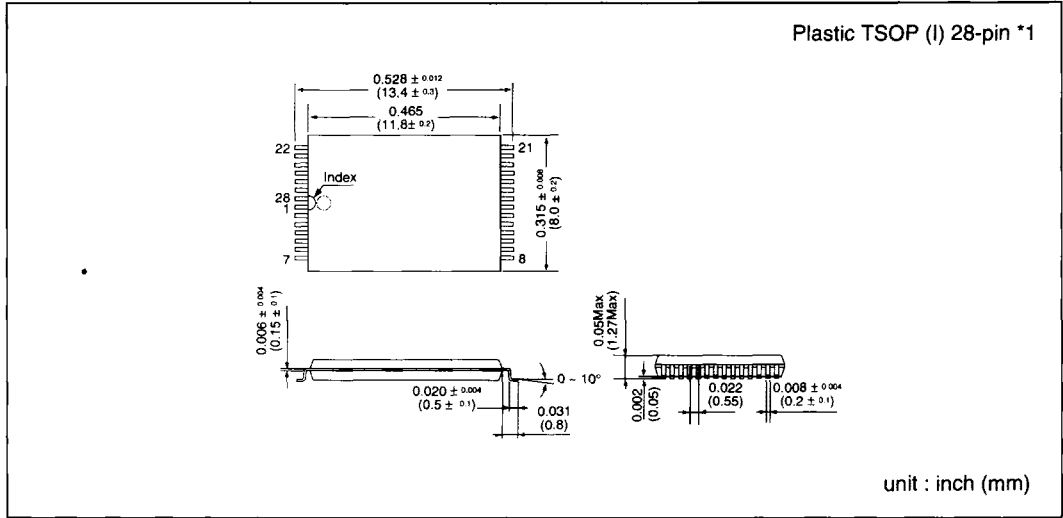
When $\overline{\text{CS}}$ is high, SRM20256LT10/12 is in the stand-by mode. In this case Data I/O terminals are in Hi-Z, so that all inputs of addresses, $\overline{\text{WE}}$ and data can be any "H" or "L". When $\overline{\text{CS}}$ is over V_{DD} - 0.2V, the SRM20256LT10/12 is in the data retention battery back-up mode. In this mode, there is a small current in the SRM20256LT10/12 which flows through the high resistances of the memory cells.

■ PACKAGE DIMENSIONS



* SRM20256LMT10/12 has the same electrical characteristics as SRM20256LCT10/12.

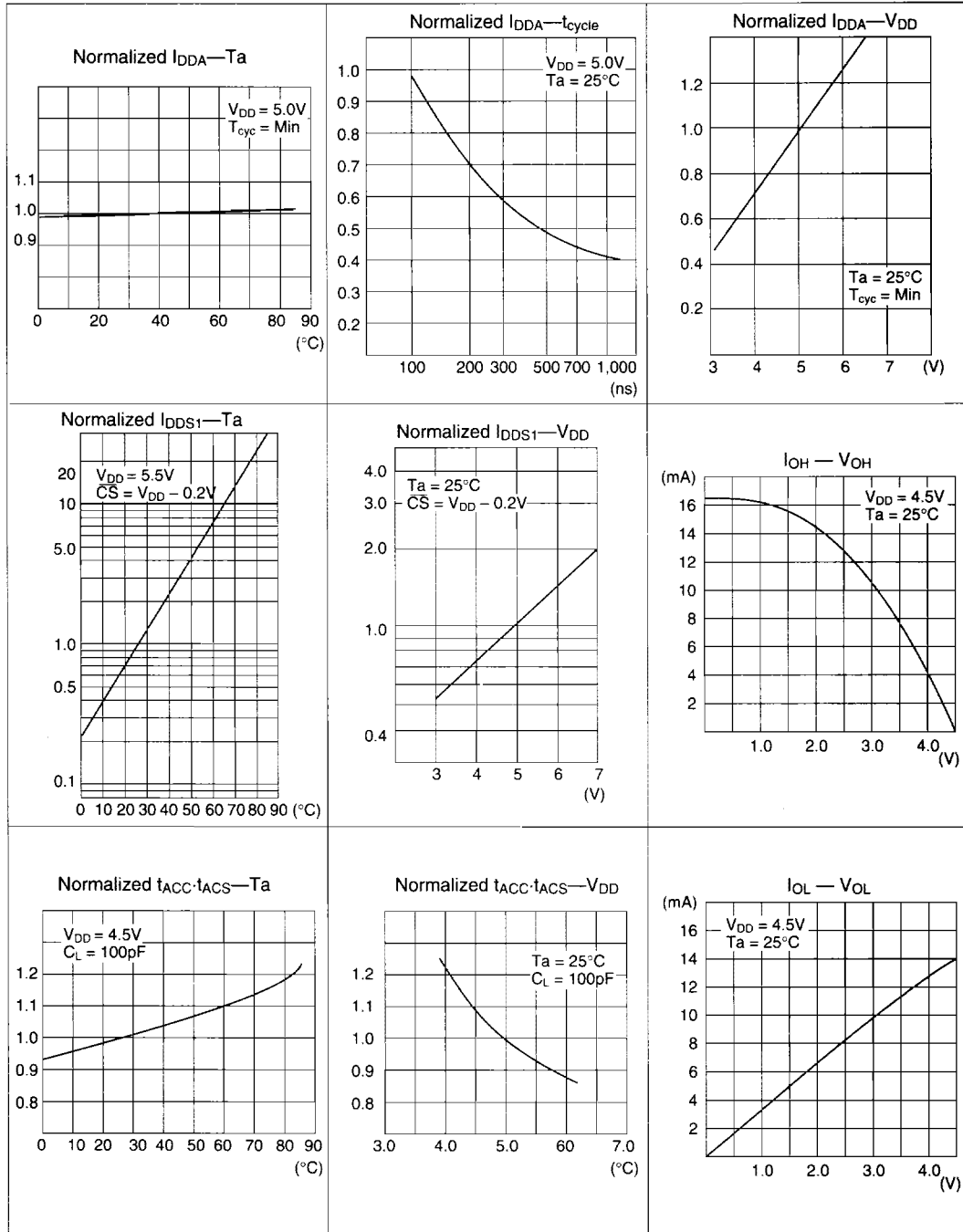
■ PACKAGE DIMENSIONS



* 1 SRM20256LTM10/12 has the same electrical characteristics as SRM20256LC10/12.

* 2 SRM20256LRM10/12 has the same electrical characteristics as SRM20256LC10/12.

■ CHARACTERISTICS CURVES



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